



Material Content Data Sheet



Sales Product Name		TLE4242G		Issued		19. July 2018		
MA#		MA001179082						
Package		PG-TO263-7-1		Weight*		1567.29 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.353	0.27	0.27	2690	2690
leadframe	non noble metal	iron	7439-89-6	0.810	0.05		500	
	inorganic material	phosphorus	7723-14-0	0.243	0.02		150	
	non noble metal	copper	7440-50-8	808.613	49.97	50.04	499732	500382
wire	non noble metal	aluminium	7429-90-5	0.385	0.02	0.02	238	238
encapsulation	organic material	carbon black	1333-86-4	1.255	0.08		776	
	plastics	epoxy resin	-	57.744	3.57		35687	
	inorganic material	silicondioxide	60676-86-0	568.657	35.14	38.79	351437	387900
leadfinish	non noble metal	tin	7440-31-5	13.037	0.81	0.81	8057	8057
plating	non noble metal	nickel	7440-02-0	0.212	0.01		131	
	inorganic material	phosphorus	7723-14-0	0.001	3.14	3.15	31395	31526
solder	noble metal	silver	7440-22-4	0.141	0.01		87	
	non noble metal	tin	7440-31-5	0.113	0.01		70	
	non noble metal	lead	7439-92-1	5.379	0.33	0.35	3325	3482
heatspreader	non noble metal	iron	7439-89-6	0.106	0.01		66	
	inorganic material	phosphorus	7723-14-0	0.032	0.00		20	
	non noble metal	copper	7440-50-8	106.210	6.56	6.57	65639	65725
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com